

Nuremberg, Germany
16.-18.3.2027



embeddedworld
Exhibition&Conference

CALL FOR PAPERS

www.embedded-world.eu

Organized by

Elektronik

NÜRNBERG / MESSE

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Comments on the Conference:

It was a very insightful event, and I found the sessions and discussions extremely valuable for our ongoing work in embedded systems.

**Omar Tapia, GE Aerospace
Mexico**

Thank you so much for the organization. We had a very good workshop with good attention to details and interest shown from the attendees.

**Dr. Muhammad Shahnawaz & Danilo Pau
STMicroelectronics, Italy**

For me as a trainer and consultant, the embedded word Conference is a fixed highlight in my calendar every year. This event increases my visibility and is an important networking opportunity for me. I have made very interesting connections at the EWC 2026.

**Stephan Gruenfelder, Heicon Global Engineering,
Austria**

The conference was fantastic again!
The class seemed to go well, and we had a lot of great questions and discussions.

**Jacob Beningo,
High-Reliability Embedded Systems Architect
Mission-Critical & Flight-Class Systems
United States**

Thanks for the opportunity to speak at embedded world Conference 2026. It was a great experience, and I appreciate all the positive feedback from the attendees of my talk.

**Rob Woolley,
Senior Principal Technologist
Wind River, United States**

embedded world Conference 2027 – 25th Edition

Connecting the Embedded Community



Established in Nuremberg in March 2003, the embedded world Conference will reach its 25th edition in 2027. The original concept of a unique combination of an exhibition for engineers and technical management on one hand and a world-leading conference at the intersection of applied research and industrial applications on the other hand has proven extremely successful. embedded world Exhibition&Conference is driven by technology as well as applications with a strong focus on system and cross domain aspects. And it is driven by the embedded community – and its annual meeting. We are **connecting the global community**:

- In times of uprising latent tensions, cold wars, and armed conflicts, we continue to believe that the interaction, the efficient cooperation of people, and good business with mutual benefits are major preconditions for a peaceful world. **embedded world North Ame-rica**¹ in September 2026 in Anaheim (CA) is now already going into its third year. The preparations for the first edition of **embedded world India**² in November 2026 in Bangalore are in full swing. We are expanding our **global reach** while further strengthening the event in Nuremberg.
- embedded world takes a holistic system approach, covering all the different aspects from research and development through to production. It brings together the key elements of modern **systems engineering of complex and dependable embedded systems**, ranging from fundamental technologies and development processes to special application domains.
- It explicitly includes important aspects like **embedded intelligence / edge AI, safety, security, connectivity**, and much more. With our cross-sectoral and interdisciplinary approach, we link these different disciplines for higher efficiency, increased sustainability, and better innovations. The audience are competent, knowledge-hungry embedded system developers, specialists, and project and product managers, who look for an intense exchange of ideas with the community. Or as we call it: from nerds for nerds.
- In order to do this, embedded world is extending its collaboration with community partners and positions itself as

community of communities. Community partners are non-profit eco-systems, foundations, or initiatives. We are extremely happy and proud of this collaboration, which has generated Special Calls for Papers (SCfP)³, and will organize dedicated sessions.

With this call, we invite you to **contribute your technical presentation or class** to the 25th edition of the embedded world Conference 2027 in Nuremberg. You are invited to present future-oriented technologies and solutions, best practices, new ideas and smart concepts for efficient development and life cycle processes. Use your presentation to initiate discussions and to help other engineers and managers to benefit from your experience.

Present a technical talk and outline your experience from technology implementations or present prototypes and application examples. Talks should be substantial, insightful and educational. Submissions promoting commercial technologies and products will not be accepted. **Application related contributions from research and pre-development** are welcome to enrich the program.

In addition to the presentations in the technical sessions, we also invite you as a lecturer of a **class** for either a half or a full day. A class deals with an in-depth topic interactively with participants and gives practical hands-on insights.

Submit your proposal using the following link: www.embedded-world.eu. The Program Committee looks forward to receiving your submission by September 28, 2026 (firm deadline). We look forward to welcoming you to the 25th edition of the embedded world Conference 2027 in Nuremberg.

A handwritten signature in blue ink, appearing to read 'A. Sikora'.

Prof. Dr.-Ing. Axel Sikora
Chairman of embedded world Conference

¹ <https://embedded-world-na.com/>

² <https://www.embedded-world-india.com/>

³ <https://embedded-world.eu/special-cfps>

Topics of interest include, but are not limited to:

1. Internet of Things & Connectivity

- 1.1 IoT Architectures & Management
- 1.2 Application Protocols & Profiles: OPC UA, MQTT, LWM2M, CANopen, Matter...
- 1.3 Software Platforms for IoT
- 1.4 Data Management, Privacy & Analytics
- 1.5 Wired Connectivity: CAN, Ethernet, TSN, ...
- 1.6 Wireless Connectivity: Bluetooth, LPWAN, NB IoT, 5G/6G, ...
- 1.7 Network Architectures & Management, Gateways
- 1.8 Application Case Studies for IoT & Connectivity

2. Embedded OS

- 2.1 RTOS: Open & Closed Source, Safety, Multicore, ...
- 2.2 Linux-based: Embedded Linux, Android, ROS
- 2.3 Cloud Integration & Services
- 2.4 Virtualization & Dockers
- 2.5 Application Case Studies: Field Updates, OTA, ...

3. Safety & Security

- 3.1 Functional Safety & Security Architectures
- 3.2 Functional Safety & Security Standards, CRA
- 3.3 Cryptography & Trusted Computing
- 3.4 Long-Term Security & Post-Quantum Cryptography
- 3.5 Hacking
- 3.6 AI-Supported Processes for Safety & Security
- 3.7 Embedded AI in Safe & Secure Systems
- 3.8 Qualification of Safe and Secure Systems
- 3.9 Application Case Studies for Safe & Secure Systems

4. Hardware Engineering

- 4.1 Microcontrollers
- 4.2 Memory
- 4.3 Sensors & Actuators
- 4.4 PCB & Packaging: High Performance, RF & Antenna Design, Printed & Flexible Electronics, ...
- 4.5 Digital Circuits & Systems: Chipllets, FPGA, ASIC, ...
- 4.6 Analog, RF & Mixed-Signal Circuits & Systems
- 4.7 Open HW at IP- and IC-Level: RISC-V, MIPS, ...
- 4.8 Energy & Power Management
- 4.9 Power Supply: Wireless, Power over Ethernet, ...
- 4.10 EDA Tools & AI-based Hardware-Design
- 4.11 Foundry Technologies
- 4.12 Application Case Studies

5. Systems & Software Engineering

- 5.1 Processes & Methods: Agile, DevOps, MLOps, MBSE, Systems Architecture, ...
- 5.2 UI Design & Design Thinking
- 5.3 AI-Assisted Engineering
- 5.4 Programming Languages: C, C++, Rust, ...
- 5.5 Coding Standards & Static Analysis: MISRA, ...
- 5.6 Quality, Test & Verification, Debugging
- 5.7 Open Source

6. Embedded Vision

- 6.1 HW Components & System Integration
- 6.2 Software Tools (incl. AI) & Toolchains
- 6.3 Standardisation (e.g. Camera Interfaces)
- 6.4 Embedded Radar, Embedded Lidar
- 6.5 Application Case Studies for Embedded Vision

7. Edge AI

- 7.1 Sensor Fusion & Integration
- 7.2 Algorithms for Embedded ML & AI
- 7.3 Hardware Support for ML & AI
- 7.4 Explainable & Predictable AI
- 7.5 Qualification of AI Systems
- 7.6 Neuromorphic Computing
- 7.7 Application Case Studies for Embedded ML/AI

8. Green and Sustainable Engineering

- 8.1 Legal Requirements and Standards
- 8.2 Engineering Ethics
- 8.3 Engineering for Sustainability & Circular Economy
- 8.4 Lifecycle Engineering

9. Application Use Cases

- 9.1 Industrial, Automation, Facility Management
- 9.2 Critical Infrastructure: Communication, Energy, Water, ...
- 9.3 Transport: Automotive, Avionics, Railway
- 9.4 Security & Defence
- 9.5 Life Sciences: Medical, Health, Wellbeing
- 9.6 Environmental, Agriculture, Marine
- 9.7 Logistics & Retail
- 9.8 Others

10. Special Calls for Papers

Acceptance:

Abstracts will be accepted based on the following criteria:

- Relevance to Audience
- Technical Soundness
- Absence of Marketing Content

Duration:

Presentations shall take advantage of the standard 30 minute time slot. Questions and answers will be covered in a separate round table discussion at the end of each session.

Slides:

Presentation slides shall be submitted before the event and will be distributed to registered attendees after the event.

Novel Ideas:

The above list represents just a selection of the topics covered. You are welcome to submit additional interesting suggestions related to the respective topics.

Language:

The conference language is English. All submissions must therefore be in English.

No Promotion:

Promotional or marketing-oriented presentations or pure product descriptions will not be accepted.

Originality:

Submissions to embedded world Conference 2027 should not have been published previously in a journal or conference proceedings, nor presented at another conference, nor currently under review or consideration for publication or presentation elsewhere.

Final Paper:

Authors of accepted submissions are invited to publish a paper in a dedicated conference proceedings volume, with full ISBN registration, page numbers, and the possibility of subsequent download.

Presenter:

A talk shall be presented by a speaker with strong public presentation skills and subject matter expertise. Multi-speaker submissions will not be accepted. The program committee reserves the right to cancel a contribution's acceptance, if the speaker, the subject or the content of the contribution was changed compared to the original submission.

The presenter guarantees to be physically present. We accept only one speaker per presentation.

Further Formats:

Class: In addition to presentations in sessions, we also invite you as a lecturer of a half- or full-day class. A class deals with an in-depth topic interactively with participants and gives practical hands-on insights.

Panel Discussion: A panel discussion brings together several experts on stage to discuss a current topic under the direction of a moderator. If you have an idea for such a panel discussion (topic of the discussion plus potential participants), we look forward to receiving your proposal.

Important Deadlines:

Abstract Submission:	28.9.2026 (firm deadline)
Notification of Authors:	m/o November, 2026
Submission of Presentations:	1.3.2027
Submission of Final Papers:	8.3.2027
embedded world Conference:	16.–18.3.2027

Please find details about the Call for Papers online at: www.embedded-world.eu

STEERING BOARD

The steering board is the strategic think tank behind the embedded world Conference. Currently six senior engineers with excellent scientific and business records, with open minds and lots of ideas, shape the future direction of the embedded world Conference. The photo was taken at Offenburg University.

(from left to right): Prof. Dr. Dirk Pesch,
Dr. Bernd Hense, Caspar Grote,
Prof. Dr. Axel Sikora, Prof. Dr. Peter Fromm,
Prof. Dr. Ansgar Meroth.
(Photo: Componeers GmbH)



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